

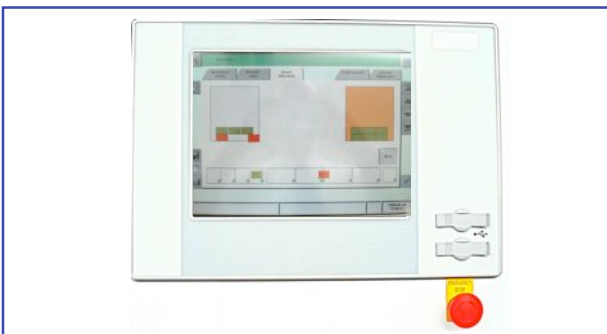
Premium In-Line Vapour Phase Soldering Machine for High Volume Production



CM 800

Features

- Fully automatic in-line-operation
- Three internal process chambers with automatic air locks
- Easy and straightforward programming of the solder data through the intuitive Touch Screen Display
- Two independent stations for loading and unloading of the carriers with Cool Handling System (no moving parts in the process chamber)
- A cycle time of under 20 sec per board is possible
- Parallel Batch and inline operation available
- Maintenance free transport system (Patented)
- Energy management system including standby mode for lowest energy consumption
- Optional IR-Heating (ideal for glue hardening)
- Optional UPS (uninterrupted power supply)



Modes of operation

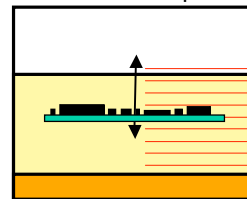
Heat Level Mode (HL-Mode)

HL-Mode is a simple method of Vapour Phase Soldering. Variable, almost linear temperature profiles are achieved by adjusting the heating power.

Soft-Vapour-Phase-Mode (SVP-Mode, Patented)

Enables extremely variable and reproducible temperature profiles to be created for different requirements.

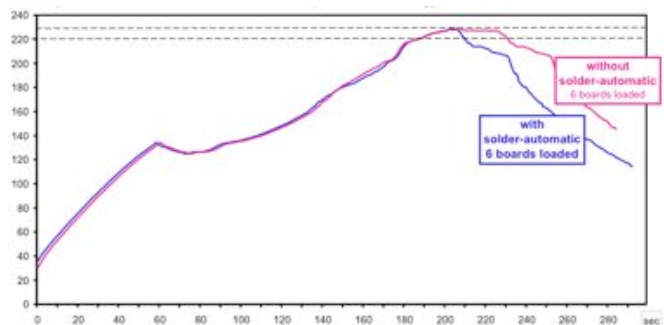
Soft-Vapour phase is the ability to control the speed the board enters the vapour and hold it at different positions. The board can be moved up or down within the vapour chamber. All steps are programmable,



Easily programmable vapour steps allow optimum adjustments of heat transfer in 20 steps

Automatic Mode

The solder automatic provides a reliable soldering performance and optimises the residual time of the boards in the vapour phase to minimise thermal stress



Limitation of the time above liquidus

After the solder temperature is reached a timer will begin. The solder cycle will finish automatically after the adjusted time over liquidus.

Documentation

Production data can be stored using the IBL VP-Control software.

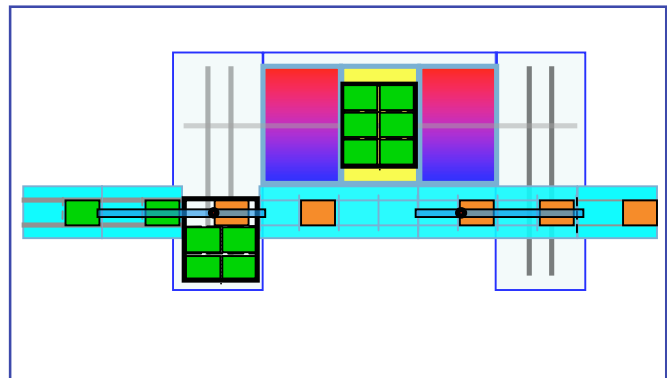
Standard Equipment / Specification

- Automatic loading and unloading of the carriers
- Integrated automatic loading and unloading conveyors
- Automatic adjustment of work piece carrier rails and mid supports
- SMEMA-Interface
- Optional IR unit for extended preheating from above
- SVP for soft temperature rise (Patented)
- Observation window to process chamber
- Integrated lighting of the soldering area
- Continuous automatic liquid agent filtering
- Double control for monitoring the cooling water temperature
- Temperature control of heater surface with thermocouple
- Integrated cooling chamber for board cooling
- Fluid level check and control
- Automatic Work piece carrier temperature compensation
- Signal lights post (red-green-blue)
- Fluid recovery system
- Variable energy level set-up
- Maintenance free high-grade steel transportation system (Patented)
- Patented process procedure
- Operation of integrated PC with TFT-Panel

Options

- Siemens-Interface
- Cooling device for closed loop machine cooling
- Additional batch carriers for manual operation
- Additional multi line carrier for 3 lines with middle support
- UPS (uninterrupted power supply)
- Full-Traceability option with integrated code scanner

- All options can be retro-fitted -



Technical Data CM 800

Length (overall)	5.950 mm incl. loading and unloading conveyor
Width	2.570 mm
Height	1.500 mm
Weight	2.000 kg
Loading/Unloading level, approx.	870-950 mm (variable)
Maximum PCB size (manual loading / In-Line-operation)	825 x 650 x 80 mm (680 x 500 x 50 mm)
Liquid agent filling	30-35 kg
Water connection	1/2"
Max. heating capacity of Vapour Phase heater / IR-heater / Ø power consumption	10,4 kW / 8kW / 5,5 kWh
Power supply / main fuse	400/230 VAC, 16 kW / 32 A, Type "gL" or "C"

- Technical changes reserved -